

# DATA SHEET



## **SAA5264; SAA5265** 10 and 1 page intelligent teletext decoders

Preliminary specification  
Supersedes data of 1999 Oct 05  
File under Integrated Circuits, IC02

2000 Jan 27

## 10 and 1 page intelligent teletext decoders

## SAA5264; SAA5265

### FEATURES

The following features apply to both SAA5264 and SAA5265:

- Complete 625 line teletext decoder in one chip reduces printed circuit board area and cost
- Automatic detection of transmitted fasttext links or service information (packet 8/30)
- On-Screen Display (OSD) for user interface menus using teletext and dedicated menu icons
- Video Programming System (VPS) decoding
- Wide Screen Signalling (WSS) decoding
- Pan-European, Cyrillic, Greek/Turkish and French/Arabic character sets in each chip
- High-level command interface via I<sup>2</sup>C-bus gives easy control with a low software overhead
- High-level command interface is backward compatible to Stand-Alone Fasttext And Remote Interface (SAFARI)
- 625 and 525 line display
- RGB interface to standard colour decoder ICs, current source
- Versatile 8-bit open-drain Input/Output (I/O) expander, 5 V tolerant
- Single 12 MHz crystal oscillator
- 3.3 V supply voltage.

### SAA5264 features

- Automatic detection of transmitted pages to be selected by page up and page down
- 8 Page fasttext decoder
- Table Of Pages (TOP) decoder with Basic Top Table (BTT) and Additional Information Tables (AITs)
- 4 Page user-defined list mode.



### GENERAL DESCRIPTION

The SAA5264 is a single-chip ten page 625-line World System Teletext decoder with a high-level command interface, and is SAFARI compatible.

The SAA5265 is a single-chip one page version of the SAA5264.

Both devices are designed to minimize the overall system cost, due to the high-level command interface offering the benefit of a low software overhead in the TV microcontroller.

The SAA5264 has the following functionality:

- 10 page teletext decoder with OSD, Fasttext, TOP, default and list acquisition modes
- Automatic channel installation support
- Closed caption acquisition and display
- Violence Chip (VChip) support.

The SAA5265 has the following functionality:

- 1 Page teletext decoder with OSD, fasttext and default acquisition modes
- Automatic channel installation support
- Closed caption acquisition and display
- VChip support
- No EEPROM fitted (there is no list mode feature).

## 10 and 1 page intelligent teletext decoders

## SAA5264; SAA5265

## ORDERING INFORMATION

TYPE NUMBER <sup>(1)</sup>	PACKAGE		
	NAME	DESCRIPTION	VERSION
SAA5264PS/M3/nnnn	SDIP52	plastic shrink dual-in-line package; 52 leads (600 mil)	SOT247-1
SAA5265PS/M4/nnnn	SDIP52	plastic shrink dual-in-line package; 52 leads (600 mil)	SOT247-1

**Note**

1. 'nnnn' is a unique four digit number denoting the software version.

## QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$V_{DDX}$	all supply voltages	referenced to $V_{SS}$	3.0	3.3	3.6	V
$I_{DDP}$	periphery supply current	note 1	1	–	–	mA
$I_{DDC}$	core supply current	normal mode	–	15	18	mA
		idle mode	–	4.6	6	mA
$I_{DDA}$	analog supply current	normal mode	–	45	48	mA
		idle mode	–	0.87	1	mA
$f_{xtal(nom)}$	nominal crystal frequency	fundamental mode	–	12	–	MHz
$T_{amb}$	ambient temperature		–20	–	+70	°C
$T_{stg}$	storage temperature		–55	–	+125	°C

**Note**

1. Periphery supply current is dependent on external components and I/O voltage levels.

10 and 1 page intelligent teletext decoders

SAA5264; SAA5265

BLOCK DIAGRAM

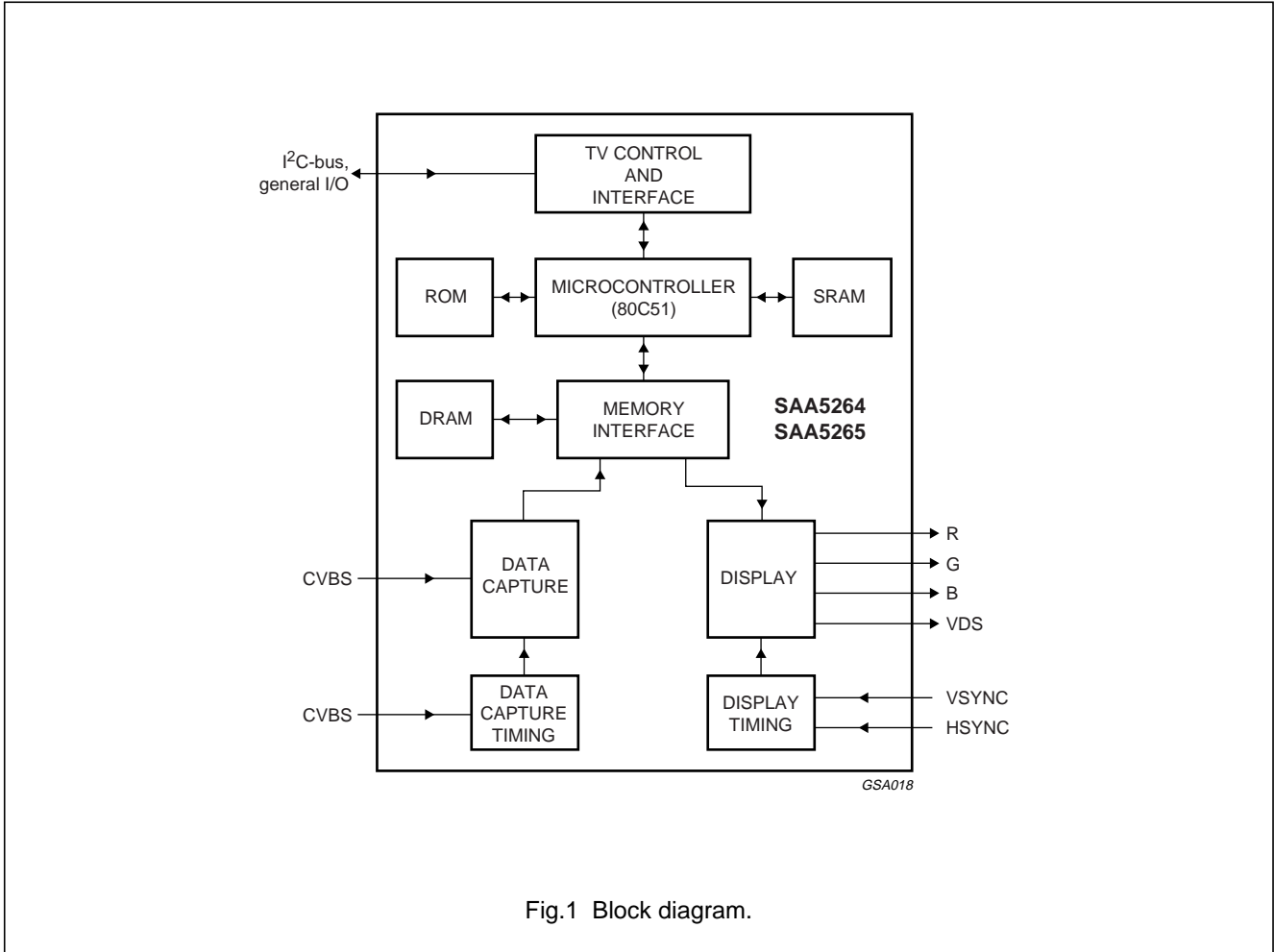


Fig.1 Block diagram.

## 10 and 1 page intelligent teletext decoders

## SAA5264; SAA5265

## PINNING

SYMBOL	PIN	TYPE	DESCRIPTION
<b>Port 2: 8-bit programmable bidirectional port with alternative functions</b>			
P2.0/PWM	1	I/O	output for 14-bit high precision Pulse Width Modulator (PWM)
P2.1/PWM0	2	I/O	outputs for 6-bit PWMs 0 to 6
P2.2/PWM1	3	I/O	
P2.3/PWM2	4	I/O	
P2.4/PWM3	5	I/O	
P2.5/PWM4	6	I/O	
P2.6/PWM5	7	I/O	
P2.7/PWM6	8	I/O	
<b>Port 3: 8-bit programmable bidirectional port with alternative functions</b>			
P3.0/ADC0	9	I/O	inputs for the software Analog-to-Digital-Converter (ADC) facility
P3.1/ADC1	10	I/O	
P3.2/ADC2	11	I/O	
P3.3/ADC3	12	I/O	
P3.4/PWM7	30	I/O	output for 6-bit PWM7
V <sub>SSC</sub>	13	–	core ground
<b>Port 0: 8-bit programmable bidirectional port</b>			
SCL(NVRAM)	14	I	I <sup>2</sup> C-bus Serial Clock input to Non-Volatile RAM
SDA(NVRAM)	15	I/O	I <sup>2</sup> C-bus Serial Data input/output (Non-Volatile RAM)
P0.2	16	I/O	input/output for general use
P0.3	17	I/O	input/output for general use
P0.4	18	I/O	input/output for general use
P0.5	19	I/O	8 mA current sinking capability for direct drive of Light Emitting Diodes (LEDs)
P0.6	20	I/O	
P0.7	21	I/O	input/output for general use
V <sub>SSA</sub>	22	–	analog ground
CVBS0	23	I	Composite Video Baseband Signal (CVBS) input; a positive-going 1 V (peak-to-peak) input is required; connected via a 100 nF capacitor
CVBS1	24	I	
SYNC_FILTER	25	I	sync-pulse-filter input for CVBS; this pin should be connected to V <sub>SSA</sub> via a 100 nF capacitor
IREF	26	I	reference current input for analog circuits; for correct operation a 24 kΩ resistor should be connected to V <sub>SSA</sub>
FRAME	27	O	Frame de-interlace output synchronized with the VSYNC pulse to produce a non-interlaced display by adjustment of the vertical deflection circuits
TEST	28	I	not available; connect this pin to V <sub>SSA</sub>
COR	29	O	contrast reduction: open-drain, active LOW output which allows selective contrast reduction of the TV picture to enhance a mixed mode display
	30	I/O	P3.4/PWM7 (described above)
V <sub>DDA</sub>	31	–	analog supply voltage (3.3 V)
B	32	O	Blue colour information pixel rate output

## 10 and 1 page intelligent teletext decoders

## SAA5264; SAA5265

SYMBOL	PIN	TYPE	DESCRIPTION
G	33	O	Green colour information pixel rate output
R	34	O	Red colour information pixel rate output
VDS	35	O	video/data switch push-pull output for pixel rate fast blanking
HSYNC	36	I	horizontal sync pulse input; Schmitt triggered for a Transistor Transistor Level (TTL) version; the polarity of this pulse is programmable by register bit TXT1.H POLARITY
VSYNC	37	I	vertical sync pulse input; Schmitt triggered for a TTL version; the polarity of this pulse is programmable by register bit TXT1.V POLARITY
V <sub>SSP</sub>	38	–	periphery ground
V <sub>DDC</sub>	39	–	core supply voltage (+3.3 V)
OSCGND	40	–	crystal oscillator ground
XTALIN	41	I	12 MHz crystal oscillator input
XTALOUT	42	O	12 MHz crystal oscillator output
RESET	43	I	reset input; if this pin is HIGH for at least 2 machine cycles (24 oscillator periods) while the oscillator is running, the device resets; this pin should be connected to V <sub>DDP</sub> via a capacitor
V <sub>DDP</sub>	44	–	periphery supply voltage (+3.3 V)
<b>Port 1: 8-bit programmable bidirectional port</b>			
P1.0	45	I/O	input/output for general use
P1.1	46	I/O	input/output for general use
P1.2	47	I/O	input/output for general use
P1.3	48	I/O	input/output for general use
SCL	49	I	I <sup>2</sup> C-bus Serial Clock input from application
SDA	50	I/O	I <sup>2</sup> C-bus Serial Data input/output (application)
P1.4	51	I/O	input/output for general use
P1.5	52	I/O	input/output for general use

10 and 1 page intelligent teletext decoders

SAA5264; SAA5265

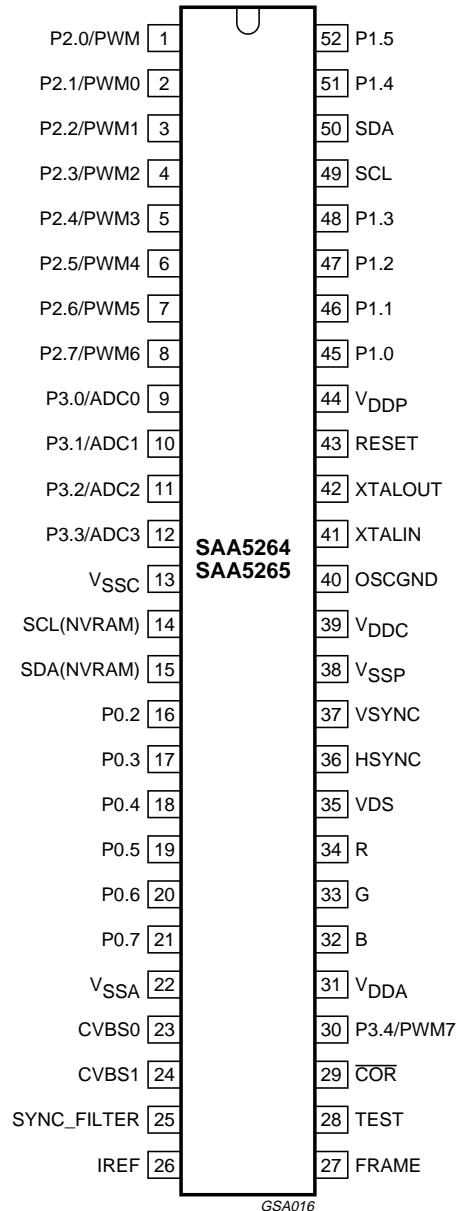


Fig.2 Pin configuration.

## 10 and 1 page intelligent teletext decoders

## SAA5264; SAA5265

**HIGH LEVEL COMMAND INTERFACE**

The I<sup>2</sup>C-bus interface is used to pass control commands and data between the SAA5264/SAA5265 and the television microcontroller. The interface uses high-level commands, which are backward compatible with the SAFARI.

The I<sup>2</sup>C-bus transmission formats are:

**Table 1** User command

START	I <sup>2</sup> C-BUS ADDRESS	WRITE	ACK	COMMAND	ACK	STOP
-------	------------------------------	-------	-----	---------	-----	------

**Table 2** System command

START	I <sup>2</sup> C-BUS ADDRESS	WRITE	ACK	COMMAND	ACK	PARAMETER	ACK	STOP
-------	------------------------------	-------	-----	---------	-----	-----------	-----	------

**Table 3** User read

START	I <sup>2</sup> C-BUS ADDRESS	READ	ACK	DATA	ACK	STOP
-------	------------------------------	------	-----	------	-----	------

**CHARACTER SETS**

The following standard character sets are included in the SAA5264 and in the SAA5265:

Set 0 = Pan-European

Set 1 = Cyrillic

Set 2 = Greek/Turkish

Set 3 = French/Arabic

If you require any other character sets, please discuss them with your local Regional Sales Office first.

**LIMITING VALUES**

In accordance with Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>DDX</sub>	all supply voltages		-0.5	+4.0	V
V <sub>I</sub>	input voltage (any input)	note 1	-0.5	V <sub>DD</sub> + 0.5 or +4.1	V
V <sub>O</sub>	output voltage (any output)	note 1	-0.5	V <sub>DD</sub> + 0.5	V
I <sub>O</sub>	output current (each output)		-	10	mA
I <sub>IO(d)</sub>	diode DC input or output current		-	20	mA
T <sub>amb</sub>	ambient temperature		-20	+70	°C
T <sub>stg</sub>	storage temperature		-55	+125	°C

**Note**

1. This maximum value refers to 5 V tolerant I/Os and may be 6 V maximum but only when V<sub>DD</sub> is present.



## 10 and 1 page intelligent teletext decoders

## SAA5264; SAA5265

**CHARACTERISTICS**

$V_{DD} = 3.3 \text{ V} \pm 10\%$ ;  $V_{SS} = 0 \text{ V}$ ;  $T_{amb} = -20 \text{ to } +70 \text{ }^\circ\text{C}$ ; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
<b>Supplies</b>						
$V_{DDX}$	all supply voltages	referenced to $V_{SS}$	3.0	3.3	3.6	V
$I_{DDP}$	periphery supply current	note 1	1	–	–	mA
$I_{DDC}$	core supply current	normal mode	–	15	18	mA
$I_{DDC}(\text{idle})$	idle mode core supply current		–	4.6	6	mA
$I_{DDA}$	analog supply current		–	45	48	mA
$I_{DDA}(\text{idle})$	idle mode analog supply current	normal mode	–	0.87	1	mA
<b>Digital inputs</b>						
RESET (PIN 43)						
$V_{IL}$	LOW-level input voltage		–	–	1.00	V
$V_{IH}$	HIGH-level input voltage		1.85	–	–	V
$V_{hys}$	Schmitt trigger input hysteresis voltage		0.44	–	0.58	V
$I_{LI}$	input leakage current	$V_I = 0$	–	–	0.17	$\mu\text{A}$
$R_{pd(\text{eq})}$	equivalent pull-down resistance	$V_I = V_{DD}$	55.73	70.71	92.45	$\text{k}\Omega$
HSYNC, VSYNC (PINS 36 AND 37)						
$V_{IL}$	LOW-level input voltage		–	–	0.96	V
$V_{IH}$	HIGH-level input voltage		1.80	–	–	V
$V_{hys}$	Schmitt trigger input hysteresis voltage		0.40	–	0.56	V
$I_{LI}$	Input leakage current	$V_I = 0 \text{ to } V_{DD}$	–	–	0.00	$\mu\text{A}$
<b>Digital outputs</b>						
FRAME, VDS (PINS 27 AND 35)						
$V_{OL}$	LOW-level output voltage	$I_{OL} = 3 \text{ mA}$	–	–	0.13	V
$V_{OH}$	HIGH-level output voltage	$I_{OH} = 3 \text{ mA}$	2.84	–	–	V
$t_{o(r)}$	output rise time	between 10% and 90%; $C_L = 70 \text{ pF}$	7.50	8.85	10.90	ns
$t_{o(f)}$	output fall time	between 10% and 90%; $C_L = 70 \text{ pF}$	6.70	7.97	10.00	ns

## 10 and 1 page intelligent teletext decoders

## SAA5264; SAA5265

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
<b>COR</b> (OPEN-DRAIN OUTPUT, PIN 29)						
$V_{OL}$	LOW-level output voltage	$I_{OL} = 3 \text{ mA}$	–	–	0.14	V
$V_{OH(pu)}$	HIGH-level pull-up output voltage	$I_{OL} = -3 \text{ mA}$ ; push-pull	2.84	–	–	V
$V_{IL}$	LOW-level input voltage		–	–	0.00	V
$V_{IH}$	HIGH-level input voltage		0.00	–	5.50	V
$I_{LI}$	input leakage current	$V_I = 0 \text{ to } V_{DD}$	–	–	0.12	$\mu\text{A}$
$t_{o(r)}$	output rise time	between 10% and 90%; $C_L = 70 \text{ pF}$	7.20	8.64	11.10	ns
$t_{o(f)}$	output fall time	between 10% and 90%; $C_L = 70 \text{ pF}$	4.90	7.34	9.40	ns
<b>Digital input/outputs</b>						
SCL(NVRAM), SDA(NVRAM), P0.4, P0.7, P1.0, P1.1, P2.1 TO P2.7, P3.0 TO P3.4 (PINS 14, 15, 18, 21, 45, 46, 2 TO 12, 30)						
$V_{IL}$	LOW-level input voltage		–	–	0.98	V
$V_{IH}$	HIGH-level input voltage		1.78	–	–	V
$V_{hys}$	Schmitt trigger input hysteresis voltage		0.41	–	0.55	V
$I_{LI}$	input leakage current	$V_I = 0 \text{ to } V_{DD}$	–	–	0.01	$\mu\text{A}$
$V_{OL}$	LOW-level output voltage	$I_{OL} = 4 \text{ mA}$	–	–	0.18	V
$V_{OH}$	HIGH-level output voltage	$I_{OH} = -4 \text{ mA}$ push-pull	2.81	–	–	V
$t_{o(r)}$	output rise time	between 10% and 90%; $C_L = 70 \text{ pF}$ push-pull	6.50	8.47	10.70	ns
$t_{o(f)}$	output fall time	between 10% and 90%; $C_L = 70 \text{ pF}$	5.70	7.56	10.00	ns
<b>P1.2, P1.3, P2.0</b> (PINS 47, 48, 1)						
$V_{IL}$	LOW-level input voltage		–	–	0.99	V
$V_{IH}$	HIGH-level input voltage		1.80	–	–	V
$V_{hys}$	Schmitt trigger input hysteresis voltage		0.42	–	0.56	V
$I_{LI}$	input leakage current	$V_I = 0 \text{ to } V_{DD}$	–	–	0.02	$\mu\text{A}$

## 10 and 1 page intelligent teletext decoders

## SAA5264; SAA5265

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V <sub>OL</sub>	LOW-level output voltage	I <sub>OL</sub> = 4 mA	–	–	0.17	V
V <sub>OH</sub>	HIGH-level output voltage	I <sub>OH</sub> = –4 mA push-pull	2.81	–	–	V
t <sub>o(r)</sub>	output rise time	between 10% and 90%; C <sub>L</sub> = 70 pF push-pull	7.00	8.47	10.50	ns
t <sub>o(f)</sub>	output fall time	between 10% and 90%; C <sub>L</sub> = 70 pF	5.40	7.36	9.30	ns
P0.5, P0.6 (PINS 19, 20)						
V <sub>IL</sub>	LOW-level input voltage		–	–	0.98	V
V <sub>IH</sub>	HIGH-level input voltage		1.82	–	–	V
I <sub>LI</sub>	input leakage current	V <sub>I</sub> = 0 to V <sub>DD</sub>	–	–	0.11	μA
V <sub>hys</sub>	Schmitt trigger input hysteresis voltage		0.42	–	0.58	V
V <sub>OL</sub>	LOW-level output voltage	I <sub>OL</sub> = 8 mA	–	–	0.20	V
V <sub>OH</sub>	HIGH-level output voltage	I <sub>OH</sub> = –8 mA push-pull	2.76	–	–	V
t <sub>o(r)</sub>	output rise time	between 10% and 90%; C <sub>L</sub> = 70 pF push-pull	7.40	8.22	8.80	ns
t <sub>o(f)</sub>	output fall time	between 10% and 90%; C <sub>L</sub> = 70 pF	4.20	4.57	5.20	ns
P1.4, P1.5 (OPEN-DRAIN) (PINS 51, 52)						
V <sub>IL</sub>	LOW-level input voltage		–	–	1.08	V
V <sub>IH</sub>	HIGH-level input voltage		1.99	–	–	V
V <sub>hys</sub>	Schmitt trigger input hysteresis voltage		0.49	–	0.60	V
I <sub>LI</sub>	input leakage current	V <sub>I</sub> = 0 to V <sub>DD</sub>	–	–	0.13	μA
V <sub>OL</sub>	LOW-level output voltage	I <sub>OL</sub> = 8 mA	–	–	0.35	V
t <sub>o(f)</sub>	output fall time	between 10% and 90%; C <sub>L</sub> = 70 pF	69.70	83.67	103.30	ns

## 10 and 1 page intelligent teletext decoders

## SAA5264; SAA5265

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
<b>Analog inputs</b>						
CVBS0 AND CVBS1(PINS 23 AND 24)						
$V_{\text{sync}}$	sync voltage amplitude		0.1	0.3	0.6	V
$V_{i(v)(p-p)}$	video input voltage (peak-to-peak value)		0.7	1.0	1.4	V
$Z_{\text{source}}$	source impedance		0	–	250	$\Omega$
$V_{\text{IH}}$	HIGH-level input voltage		3.0	–	$V_{\text{DDA}} + 0.3$	V
$C_i$	input capacitance		–	–	10	pF
IREF (PIN 26)						
$R_{\text{IREF}}$	resistance from IREF to $V_{\text{SSA}}$	resistor tolerance = 2%	–	24	–	k $\Omega$
ADC0 TO ADC3 (PINS 9 TO 12)						
$V_{\text{IH}}$	HIGH-level input voltage		–	–	$V_{\text{DDA}}$	V
$C_i$	input capacitance		–	–	10	pF
<b>Analog outputs</b>						
B, G AND R (PINS 32 TO 34)						
$I_{o(bl)}$	output current (black level)	$V_{\text{DDA}} = 3.3 \text{ V}$	–10	–	+10	$\mu\text{A}$
$I_{o(max)}$	output current (maximum intensity)	$V_{\text{DDA}} = 3.3 \text{ V}$ intensity level code = 15 (Dec)	6.0	6.67	7.3	mA
$I_{o(70\%max)}$	output current (70% of maximum intensity)	$V_{\text{DDA}} = 3.3 \text{ V}$ intensity level code = 0 (Dec)	4.2	4.7	5.1	mA
$R_L$	load resistance (to $V_{\text{SSA}}$ )	resistor tolerance = 5%	–	150	–	$\Omega$
$C_L$	load capacitance		–	–	15	pF
<b>Analog input/output</b>						
SYNC_FILTER (PIN 25)						
$C_{\text{stg}}$	storage capacitor (to $V_{\text{SSA}}$ )		–	100	–	nF
$V_{\text{sync(nom)}}$	sync filter level voltage with nominal sync amplitude		0.35	0.55	0.75	V

## 10 and 1 page intelligent teletext decoders

## SAA5264; SAA5265

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
<b>Crystal oscillator</b>						
XTALIN (PIN 41)						
V <sub>IL</sub>	LOW-level input voltage		V <sub>SSA</sub>	–	–	V
V <sub>IH</sub>	HIGH-level input voltage		–	–	V <sub>DDA</sub>	V
C <sub>i</sub>	input capacitance		–	–	10	pF
XTALOUT (PIN 42)						
C <sub>o</sub>	output capacitance		–	–	10	pF
<b>Crystal specification; notes 2 and 3</b>						
f <sub>xtal(nom)</sub>	nominal frequency	fundamental mode	–	12	–	MHz
C <sub>L</sub>	load capacitance		–	–	30	pF
C <sub>mot</sub>	motional capacitance	T <sub>amb</sub> = 25 °C	–	–	20	fF
R <sub>xtal</sub>	crystal resonance resistance	T <sub>amb</sub> = 25 °C	–	–	60	Ω
C <sub>osc</sub>	capacitance at XTALIN, XTALOUT	T <sub>amb</sub> = 25 °C	–	2C <sub>L</sub> – C <sub>chip</sub> – C <sub>stray</sub>	–	pF
C <sub>xtal(hold)</sub>	crystal holder capacitance	T <sub>amb</sub> = 25 °C	–	–	$35 - \frac{C_{osc}}{2} - \frac{C_{chip}}{2} - \frac{C_{stray}}{2}$	pF
T <sub>xtal</sub>	crystal temperature range		–20	+25	+85	°C
X <sub>j</sub>	adjustment tolerance	T <sub>amb</sub> = 25 °C	–	–	±50 × 10 <sup>–6</sup>	
X <sub>d</sub>	drift		–	–	±100 × 10 <sup>–6</sup>	

**Notes**

1. Periphery supply current is dependent on I/O external components and voltage levels.
2. Crystal order number 4322 143 05561. If crystal 4322 143 05561 is not used, then the formulae in the crystal specification should be used.
3. C<sub>osc</sub> may need to be reduced from the initially selected value. C<sub>chip</sub> = 7 pF, the mean of the capacitances due to the chip at XTALIN and at XTALOUT. C<sub>stray</sub> is a value for the mean of the stray capacitances due to the external circuit at XTALIN and XTALOUT. The maximum value for C<sub>xtal(hold)</sub> is to ensure start-up.

## 10 and 1 page intelligent teletext decoders

## SAA5264; SAA5265

**I<sup>2</sup>C-BUS CHARACTERISTICS**

SYMBOL	PARAMETER	FAST-MODE I <sup>2</sup> C-bus		UNIT
		MIN.	MAX.	
f <sub>SCL</sub>	SCL clock frequency	0	400	kHz
t <sub>BUF</sub>	bus free time between a STOP and START condition	1.3	–	μs
t <sub>HD;STA</sub>	hold time START condition; after this period, the first clock pulse is generated	0.6	–	μs
t <sub>LOW</sub>	SCL LOW time	1.3	–	μs
t <sub>HIGH</sub>	SCL HIGH time	0.6	–	μs
t <sub>SU;STA</sub>	set-up time repeated START	0.6	–	μs
t <sub>HD;DAT</sub>	data hold time; notes 1 and 2	0	0.9	μs
t <sub>SU;DAT</sub>	data set-up time; note 3	100	–	ns
t <sub>r</sub>	rise time SDA and SCL; note 4	20	300	ns
t <sub>f</sub>	fall time SDA and SCL; note 4	20	300	ns
t <sub>SU;STO</sub>	set-up time STOP condition	0.6	–	μs
C <sub>b</sub>	capacitive load of each bus line	–	400	pF

**Notes**

1. A device must internally provide a hold time of at least 300 ns for the SDA signal (referenced to the V<sub>IHmin</sub> of the SCL signal) in order to bridge the undefined region of the falling edge of SCL.
2. The maximum t<sub>HD;DAT</sub> has only to be met if the device does not stretch the LOW period of the SCL signal (t<sub>LOW(SCL)</sub>).
3. A fast-mode I<sup>2</sup>C-bus device can be used in a standard-mode I<sup>2</sup>C-bus system, but the requirement t<sub>SU;DAT</sub> ≥ 250 ns must then be met. This will automatically be the case if the device does not stretch t<sub>LOW(SCL)</sub>. If such a device does stretch t<sub>LOW(SCL)</sub>, it must output the next data bit to the SDA line t<sub>r(max)</sub> + t<sub>SU;DAT</sub> = 1000 + 250 = 1250 ns (according to the standard-mode I<sup>2</sup>C-bus specification) before the SCL line is released.
4. C<sub>b</sub> = total capacitance of one bus line in pF.

# 10 and 1 page intelligent teletext decoders

# SAA5264; SAA5265

### EMC GUIDELINES

Optimization of circuit return paths and minimization of common mode emission will be assisted by using a double sided Printed Circuit Board (PCB) with low inductance ground plane.

On a single-sided PCB a local ground plane under the whole IC should be present as shown in Fig.3. This should have the widest possible connection between the PCB ground and bulk electrolytic decoupling capacitor. Preferably, the PCB local ground plane connection should not be connected to other grounds on route to the PCB ground. Do not use wire links. Wire links cause ground inductance which increases ground bounce.

The supply pins can be decoupled at the ground pin plane below the IC. This is easily achieved by using surface mount capacitors, which, at high frequency, are more effective than components with leads.

Using a device socket would increase the area and therefore increase the inductance of the external bypass loop.

To provide a high-impedance to any high frequency signals on the  $V_{DD}$  supplies to the IC, a ferrite bead or inductor can be connected in series with the supply line close to the decoupling capacitor. To prevent signal radiation, pull-up resistors of signal outputs should not be connected to the  $V_{DD}$  supply on the IC side of the ferrite bead or inductor.

OSCGND should only be connected to the crystal load capacitors and not to any other ground connection.

Distances to physical connections of associated active devices should be as short as possible.

PCB output tracks should have close proximity, mutually coupled, ground return paths.

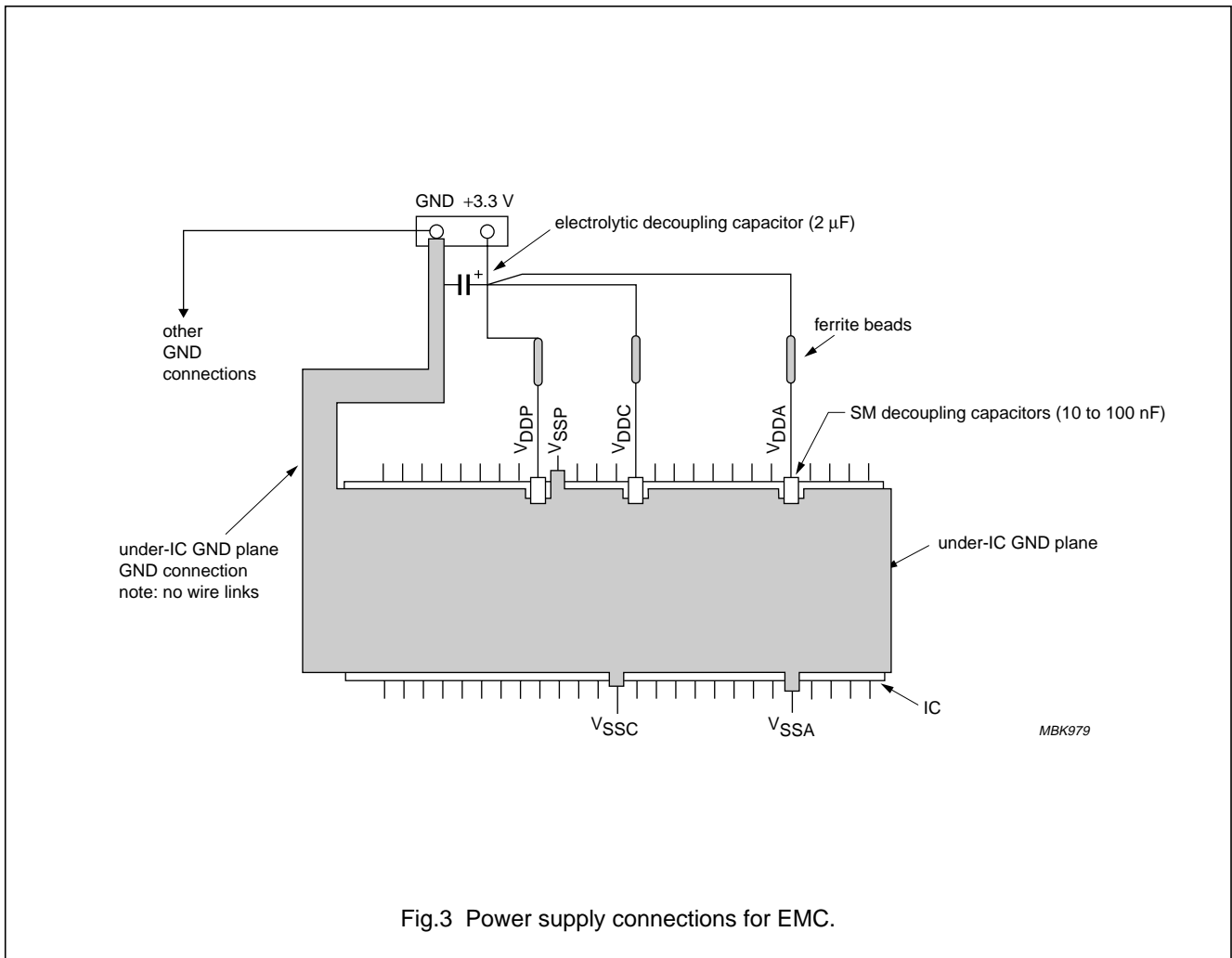


Fig.3 Power supply connections for EMC.

## 10 and 1 page intelligent teletext decoders

## SAA5264; SAA5265

**QUALITY AND RELIABILITY**

This device will meet Philips Semiconductors general quality specification for business group "Consumer Integrated Circuits SNW-FQ-611-Part E". The principal requirements are shown in Tables 4 to 7.

**Group A****Table 4** Acceptance tests per lot; note 1

TEST	REQUIREMENTS
Mechanical	cumulative target: <80 ppm
Electrical	cumulative target: <100 ppm

**Note**

1. ppm = fraction of defective devices, in parts per million.

**Group B****Table 5** Processability tests (by package family)

TEST	REQUIREMENTS
Solderability	0/16 on all lots
Mechanical	0/15 on all lots
Solder heat resistance	0/15 on all lots

**Group C****Table 6** Reliability tests (by package family); note 1

TEST	CONDITIONS	REQUIREMENTS
Operational life	168 hours at $T_j = 150\text{ }^\circ\text{C}$	<1000 FPM at $T_j = 150\text{ }^\circ\text{C}$
Humidity life	temperature, humidity, bias 1000 hours; $T_{amb} = 85\text{ }^\circ\text{C}$ , 85% RH (or equivalent test)	<2000 FPM
Temperature cycling performance	$T_{stg(min)}$ to $T_{stg(max)}$	<2000 FPM

**Note**

1. FPM = fraction of devices failing at test condition, in Failures Per Million.

**Table 7** Reliability tests (by device type)

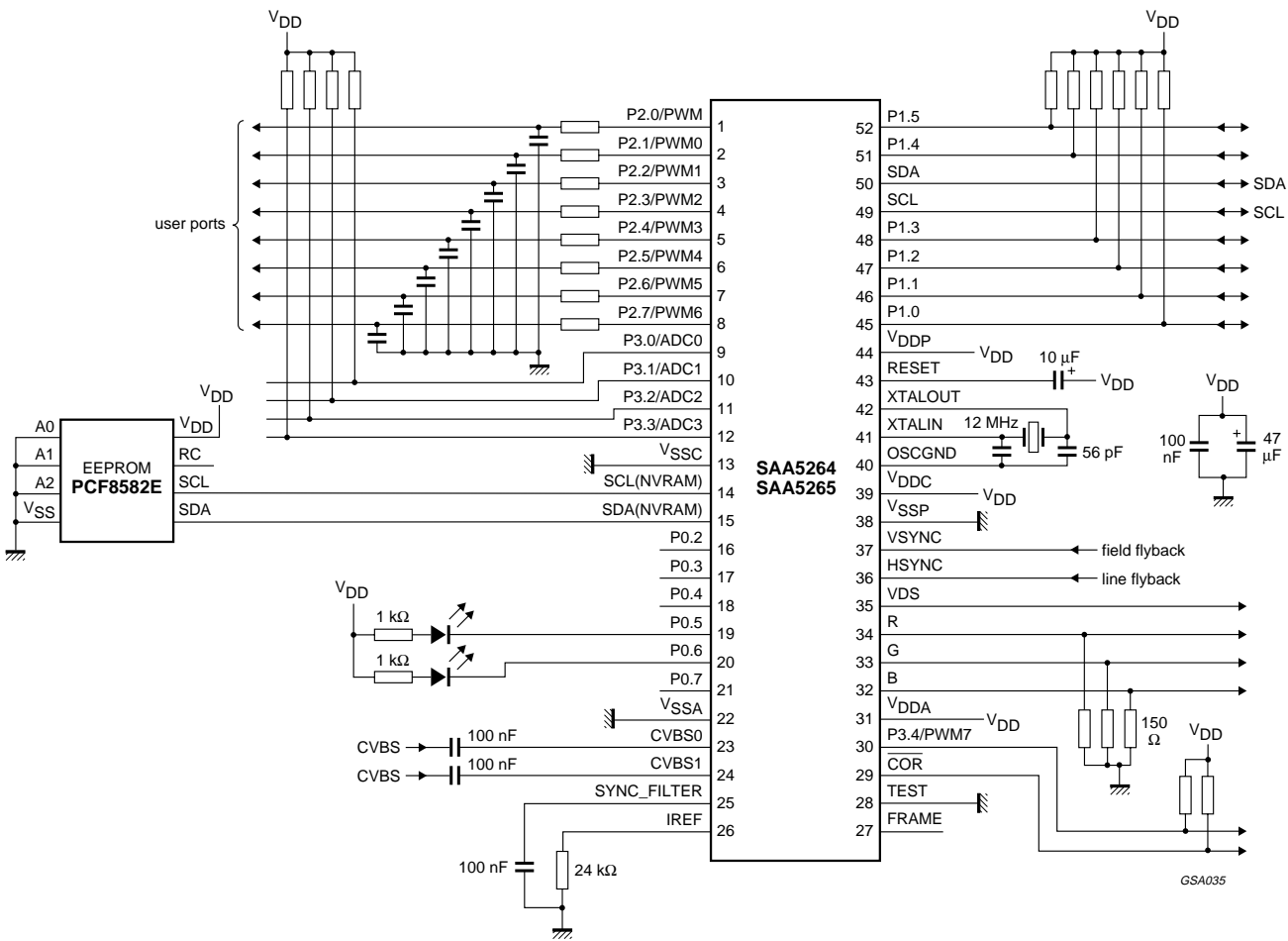
TEST	CONDITIONS	REQUIREMENTS
ESD and latch-up	ESD Human body model 100 pF, 1.5 k $\Omega$	2000 V
	ESD Machine model 200 pF, 0 $\Omega$	200 V
	latch-up	100 mA, $1.5 \times V_{DD}$ (absolute maximum)



10 and 1 page intelligent teletext decoders

SAA5264; SAA5265

APPLICATION INFORMATION



Bi-directional ports have been configured as open-drain. Output ports have been configured as push-pull.

Fig.4 Application diagram.

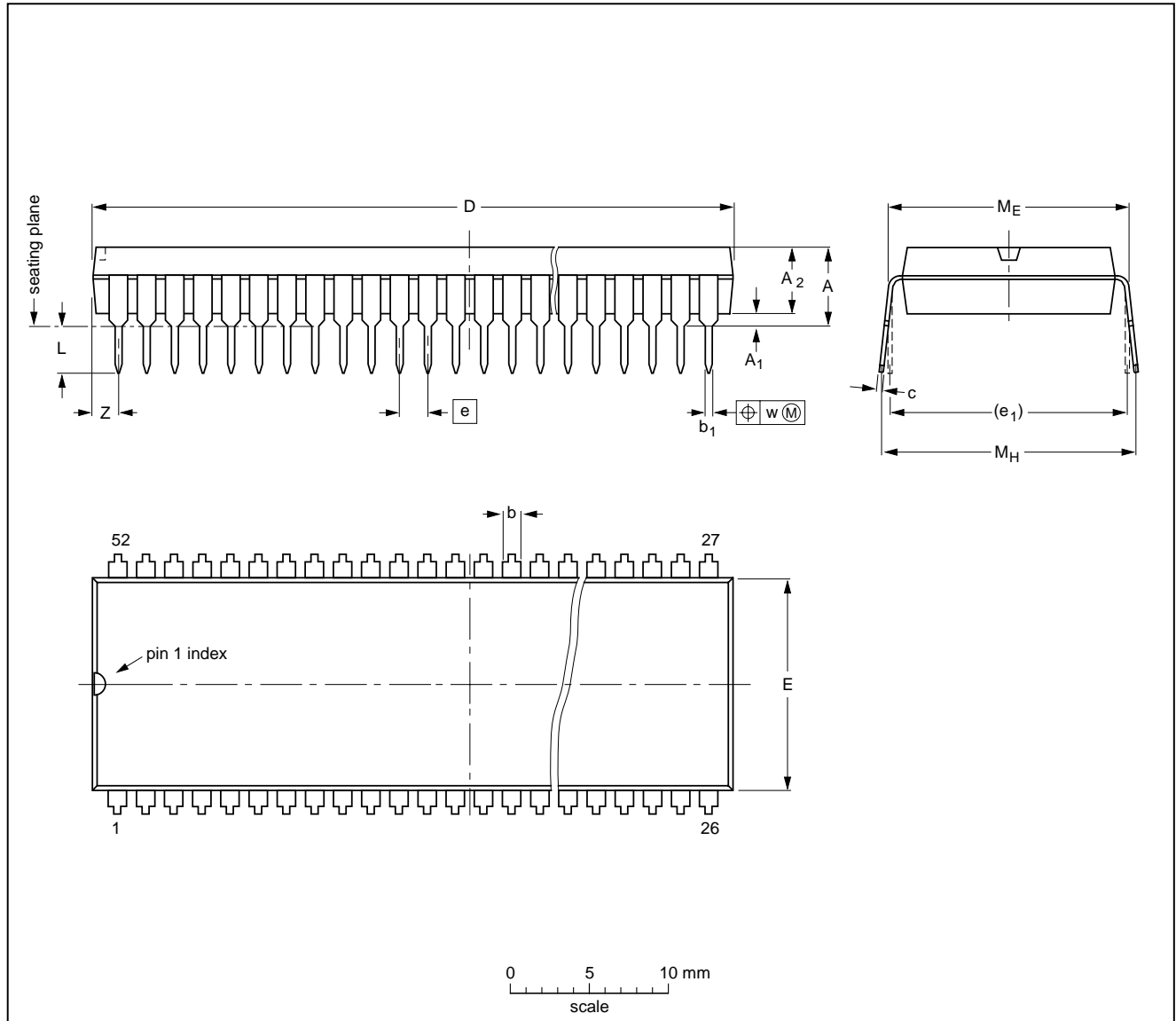
10 and 1 page intelligent teletext decoders

SAA5264; SAA5265

PACKAGE OUTLINE

SDIP52: plastic shrink dual in-line package; 52 leads (600 mil)

SOT247-1



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A <sub>1</sub> min.	A <sub>2</sub> max.	b	b <sub>1</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	e <sub>1</sub>	L	M <sub>E</sub>	M <sub>H</sub>	w	Z <sup>(1)</sup> max.
mm	5.08	0.51	4.0	1.3 0.8	0.53 0.40	0.32 0.23	47.9 47.1	14.0 13.7	1.778	15.24	3.2 2.8	15.80 15.24	17.15 15.90	0.18	1.73

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT247-1		MS-020				<del>95-03-11</del> 99-12-27

## 10 and 1 page intelligent teletext decoders

## SAA5264; SAA5265

**SOLDERING****Introduction to soldering through-hole mount packages**

This text gives a brief insight to wave, dip and manual soldering. A more in-depth account of soldering ICs can be found in our *"Data Handbook IC26; Integrated Circuit Packages"* (document order number 9398 652 90011).

Wave soldering is the preferred method for mounting of through-hole mount IC packages on a printed-circuit board.

**Soldering by dipping or by solder wave**

The maximum permissible temperature of the solder is 260 °C; solder at this temperature must not be in contact with the joints for more than 5 seconds.

The total contact time of successive solder waves must not exceed 5 seconds.

The device may be mounted up to the seating plane, but the temperature of the plastic body must not exceed the specified maximum storage temperature ( $T_{stg(max)}$ ). If the printed-circuit board has been pre-heated, forced cooling may be necessary immediately after soldering to keep the temperature within the permissible limit.

**Manual soldering**

Apply the soldering iron (24 V or less) to the lead(s) of the package, either below the seating plane or not more than 2 mm above it. If the temperature of the soldering iron bit is less than 300 °C it may remain in contact for up to 10 seconds. If the bit temperature is between 300 and 400 °C, contact may be up to 5 seconds.

**Suitability of through-hole mount IC packages for dipping and wave soldering methods**

PACKAGE	SOLDERING METHOD	
	DIPPING	WAVE
DBS, DIP, HDIP, SDIP, SIL	suitable	suitable <sup>(1)</sup>

**Note**

- For SDIP packages, the longitudinal axis must be parallel to the transport direction of the printed-circuit board.

## 10 and 1 page intelligent teletext decoders

## SAA5264; SAA5265

**DEFINITIONS**

<b>Data sheet status</b>	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
<b>Limiting values</b>	
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.	
<b>Application information</b>	
Where application information is given, it is advisory and does not form part of the specification.	

**LIFE SUPPORT APPLICATIONS**

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.

**PURCHASE OF PHILIPS I<sup>2</sup>C COMPONENTS**

Purchase of Philips I<sup>2</sup>C components conveys a license under the Philips' I<sup>2</sup>C patent to use the components in the I<sup>2</sup>C system provided the system conforms to the I<sup>2</sup>C specification defined by Philips. This specification can be ordered using the code 9398 393 40011.

10 and 1 page intelligent teletext decoders

SAA5264; SAA5265

---

**NOTES**

10 and 1 page intelligent teletext decoders

SAA5264; SAA5265

---

**NOTES**

10 and 1 page intelligent teletext decoders

SAA5264; SAA5265

---

**NOTES**

# Philips Semiconductors – a worldwide company

**Argentina:** see South America

**Australia:** 3 Figtree Drive, HOME BUSH, NSW 2140,  
Tel. +61 2 9704 8141, Fax. +61 2 9704 8139

**Austria:** Computerstr. 6, A-1101 WIEN, P.O. Box 213,  
Tel. +43 1 60 101 1248, Fax. +43 1 60 101 1210

**Belarus:** Hotel Minsk Business Center, Bld. 3, r. 1211, Volodarski Str. 6,  
220050 MINSK, Tel. +375 172 20 0733, Fax. +375 172 20 0773

**Belgium:** see The Netherlands

**Brazil:** see South America

**Bulgaria:** Philips Bulgaria Ltd., Energoproject, 15th floor,  
51 James Bourchier Blvd., 1407 SOFIA,  
Tel. +359 2 68 9211, Fax. +359 2 68 9102

**Canada:** PHILIPS SEMICONDUCTORS/COMPONENTS,  
Tel. +1 800 234 7381, Fax. +1 800 943 0087

**China/Hong Kong:** 501 Hong Kong Industrial Technology Centre,  
72 Tat Chee Avenue, Kowloon Tong, HONG KONG,  
Tel. +852 2319 7888, Fax. +852 2319 7700

**Colombia:** see South America

**Czech Republic:** see Austria

**Denmark:** Sydhavnsgade 23, 1780 COPENHAGEN V,  
Tel. +45 33 29 3333, Fax. +45 33 29 3905

**Finland:** Sinikalliontie 3, FIN-02630 ESPOO,  
Tel. +358 9 615 800, Fax. +358 9 6158 0920

**France:** 51 Rue Carnot, BP317, 92156 SURESNES Cedex,  
Tel. +33 1 4099 6161, Fax. +33 1 4099 6427

**Germany:** Hammerbrookstraße 69, D-20097 HAMBURG,  
Tel. +49 40 2353 60, Fax. +49 40 2353 6300

**Hungary:** see Austria

**India:** Philips INDIA Ltd, Band Box Building, 2nd floor,  
254-D, Dr. Annie Besant Road, Worli, MUMBAI 400 025,  
Tel. +91 22 493 8541, Fax. +91 22 493 0966

**Indonesia:** PT Philips Development Corporation, Semiconductors Division,  
Gedung Philips, Jl. Buncit Raya Kav.99-100, JAKARTA 12510,  
Tel. +62 21 794 0040 ext. 2501, Fax. +62 21 794 0080

**Ireland:** Newstead, Clonskeagh, DUBLIN 14,  
Tel. +353 1 7640 000, Fax. +353 1 7640 200

**Israel:** RAPAC Electronics, 7 Kehilat Saloniki St, PO Box 18053,  
TEL AVIV 61180, Tel. +972 3 645 0444, Fax. +972 3 649 1007

**Italy:** PHILIPS SEMICONDUCTORS, Via Casati, 23 - 20052 MONZA (MI),  
Tel. +39 039 203 6838, Fax +39 039 203 6800

**Japan:** Philips Bldg 13-37, Kohnan 2-chome, Minato-ku,  
TOKYO 108-8507, Tel. +81 3 3740 5130, Fax. +81 3 3740 5057

**Korea:** Philips House, 260-199 Itaewon-dong, Yongsan-ku, SEOUL,  
Tel. +82 2 709 1412, Fax. +82 2 709 1415

**Malaysia:** No. 76 Jalan Universiti, 46200 PETALING JAYA, SELANGOR,  
Tel. +60 3 750 5214, Fax. +60 3 757 4880

**Mexico:** 5900 Gateway East, Suite 200, EL PASO, TEXAS 79905,  
Tel. +9-5 800 234 7381, Fax +9-5 800 943 0087

**Middle East:** see Italy

**Netherlands:** Postbus 90050, 5600 PB EINDHOVEN, Bldg. VB,  
Tel. +31 40 27 82785, Fax. +31 40 27 88399

**New Zealand:** 2 Wagener Place, C.P.O. Box 1041, AUCKLAND,  
Tel. +64 9 849 4160, Fax. +64 9 849 7811

**Norway:** Box 1, Manglerud 0612, OSLO,  
Tel. +47 22 74 8000, Fax. +47 22 74 8341

**Pakistan:** see Singapore

**Philippines:** Philips Semiconductors Philippines Inc.,  
106 Valero St. Salcedo Village, P.O. Box 2108 MCC, MAKATI,  
Metro MANILA, Tel. +63 2 816 6380, Fax. +63 2 817 3474

**Poland:** Al.Jerozolimskie 195 B, 02-222 WARSAW,  
Tel. +48 22 5710 000, Fax. +48 22 5710 001

**Portugal:** see Spain

**Romania:** see Italy

**Russia:** Philips Russia, Ul. Usatcheva 35A, 119048 MOSCOW,  
Tel. +7 095 755 6918, Fax. +7 095 755 6919

**Singapore:** Lorong 1, Toa Payoh, SINGAPORE 319762,  
Tel. +65 350 2538, Fax. +65 251 6500

**Slovakia:** see Austria

**Slovenia:** see Italy

**South Africa:** S.A. PHILIPS Pty Ltd., 195-215 Main Road Martindale,  
2092 JOHANNESBURG, P.O. Box 58088 Newville 2114,  
Tel. +27 11 471 5401, Fax. +27 11 471 5398

**South America:** Al. Vicente Pinzon, 173, 6th floor,  
04547-130 SÃO PAULO, SP, Brazil,  
Tel. +55 11 821 2333, Fax. +55 11 821 2382

**Spain:** Balmes 22, 08007 BARCELONA,  
Tel. +34 93 301 6312, Fax. +34 93 301 4107

**Sweden:** Kottbygatan 7, Akalla, S-16485 STOCKHOLM,  
Tel. +46 8 5985 2000, Fax. +46 8 5985 2745

**Switzerland:** Allmendstrasse 140, CH-8027 ZÜRICH,  
Tel. +41 1 488 2741 Fax. +41 1 488 3263

**Taiwan:** Philips Semiconductors, 6F, No. 96, Chien Kuo N. Rd., Sec. 1,  
TAIPEI, Taiwan Tel. +886 2 2134 2886, Fax. +886 2 2134 2874

**Thailand:** PHILIPS ELECTRONICS (THAILAND) Ltd.,  
209/2 Sanpavuth-Bangna Road Prakanong, BANGKOK 10260,  
Tel. +66 2 745 4090, Fax. +66 2 398 0793

**Turkey:** Yukari Dudullu, Org. San. Blg., 2.Cad. Nr. 28 81260 Umraniye,  
ISTANBUL, Tel. +90 216 522 1500, Fax. +90 216 522 1813

**Ukraine:** PHILIPS UKRAINE, 4 Patrice Lumumba str., Building B, Floor 7,  
252042 KIEV, Tel. +380 44 264 2776, Fax. +380 44 268 0461

**United Kingdom:** Philips Semiconductors Ltd., 276 Bath Road, Hayes,  
MIDDLESEX UB3 5BX, Tel. +44 208 730 5000, Fax. +44 208 754 8421

**United States:** 811 East Arques Avenue, SUNNYVALE, CA 94088-3409,  
Tel. +1 800 234 7381, Fax. +1 800 943 0087

**Uruguay:** see South America

**Vietnam:** see Singapore

**Yugoslavia:** PHILIPS, Trg N. Pasica 5/v, 11000 BEOGRAD,  
Tel. +381 11 3341 299, Fax.+381 11 3342 553

**For all other countries apply to:** Philips Semiconductors,  
International Marketing & Sales Communications, Building BE-p, P.O. Box 218,  
5600 MD EINDHOVEN, The Netherlands, Fax. +31 40 27 24825

**Internet:** <http://www.semiconductors.philips.com>

© Philips Electronics N.V. 2000

SCA 69

All rights are reserved. Reproduction in whole or in part is prohibited without the prior written consent of the copyright owner.

The information presented in this document does not form part of any quotation or contract, is believed to be accurate and reliable and may be changed without notice. No liability will be accepted by the publisher for any consequence of its use. Publication thereof does not convey nor imply any license under patent- or other industrial or intellectual property rights.

Printed in The Netherlands

753504/02/pp24

Date of release: 2000 Jan 27

Document order number: 9397 750 06789

*Let's make things better.*

**Philips**  
Semiconductors



**PHILIPS**